

## 2SJ402-VB Datasheet

# P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
- 60	0.019 at V <sub>GS</sub> = - 10 V	- 80	76 nC			
	0.025 at V <sub>GS</sub> = - 4.5 V	- 70	70110			

### **FEATURES**

- TrenchFET® Power MOSFET
- 100 % UIS Tested

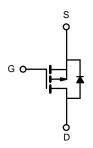


#### **APPLICATIONS**

Load Switch







P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 60			
Gate-Source Voltage	$V_{GS}$	± 20	\ \ \ \		
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		- 80 <sup>a</sup>		
	T <sub>C</sub> = 70 °C	, <u> </u>	- 70	А	
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	9.2 <sup>b</sup>		
	T <sub>A</sub> = 70 °C		- 8.1 <sup>b</sup>		
Pulsed Drain Current		I <sub>DM</sub>	- 150		
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	- 45		
Single Pulse Avalanche Energy		E <sub>AS</sub>	101	mJ	
0 0 0	T <sub>C</sub> = 25 °C	1	69 <sup>a</sup>	А	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	Is	2.1 <sup>b</sup>		
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		104.2 <sup>a</sup>		
	T <sub>C</sub> = 70 °C		66.7 <sup>a</sup>	١٨,	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	W	
	T <sub>A</sub> = 70 °C		2 <sup>b</sup>		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	$R_{thJA}$	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.98	1.2	]	

#### Notes:

- a. Based on  $T_C$  = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	$\Delta V_{DS}/T_J$ $I_D = -250 \mu\text{A}$		68		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	1 <sub>D</sub> = - 230 μΑ		- 5.2		IIIV/ C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V			- 1		
		V <sub>DS</sub> = - 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	μA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = - 5 V, V <sub>GS</sub> = - 10 V	- 120			Α	
Drain-Source On-State Resistance <sup>a</sup>		V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 30 A		0.019		Ω	
	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 20 A		0.025			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 50 A	20			S	
Dynamic <sup>b</sup>				1	·		
Input Capacitance	C <sub>iss</sub>			3500		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		390			
Reverse Transfer Capacitance	C <sub>rss</sub>			290			
T. 10 O	Q <sub>g</sub>	$V_{DS} = -30 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -55 \text{ A}$		76			
Total Gate Charge				38			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -55 \text{ A}$		16		nC	
Gate-Drain Charge	$Q_{gd}$			19			
Gate Resistance	R <sub>g</sub>	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = -2 V, R_L = 2 \Omega$		7	15	ns	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong$ - 10 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		70	110		
Fall Time	t <sub>f</sub>			40	60		
<b>Drain-Source Body Diode Characteristic</b>	s						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 69	^	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 150	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 30 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = - 50 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		45	68	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			59	120	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			29			
Reverse Recovery Rise Time	t <sub>b</sub>			16		ns	

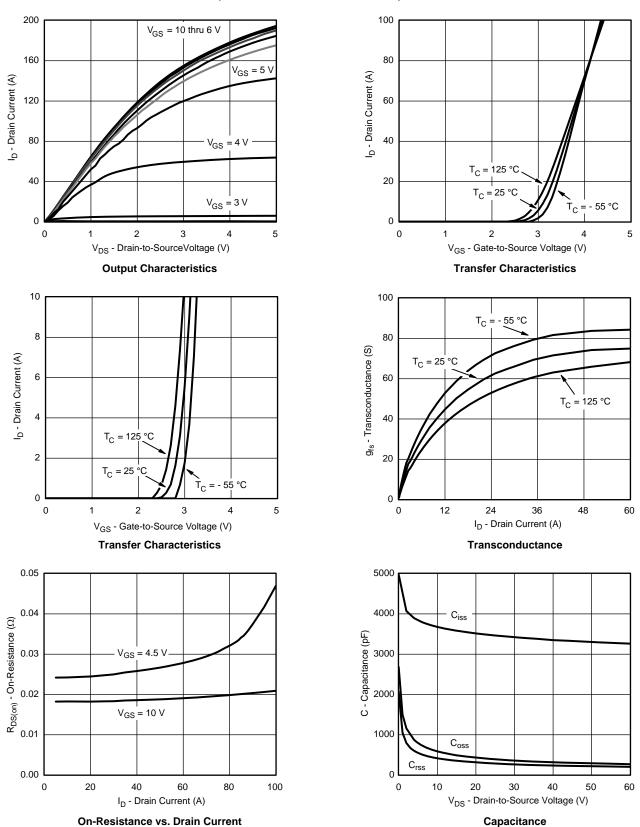
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

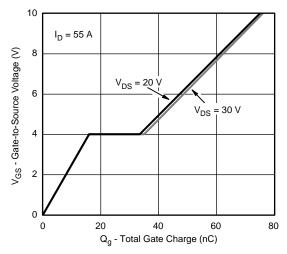


### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

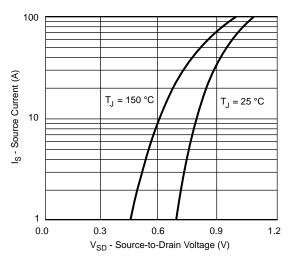




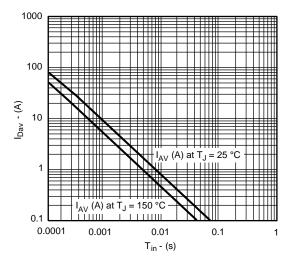
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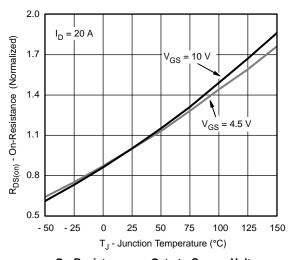
#### **Gate Charge**



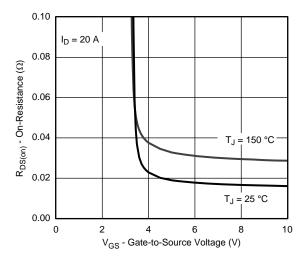
Source-Drain Diode Forward Voltage



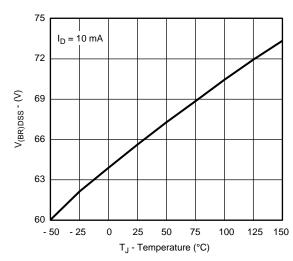
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



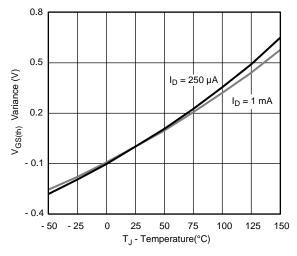
On-Resistance vs. Gate-to-Source Voltage

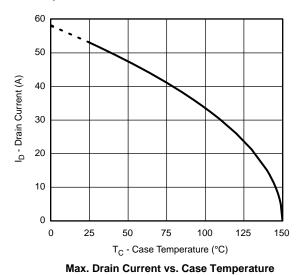


Drain-Source Breakdown Voltage vs. Junction Temperature



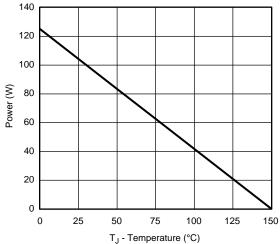
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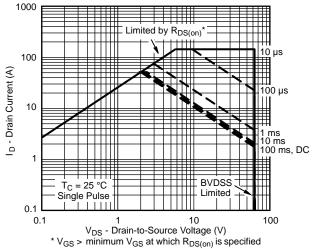




Threshold Voltage

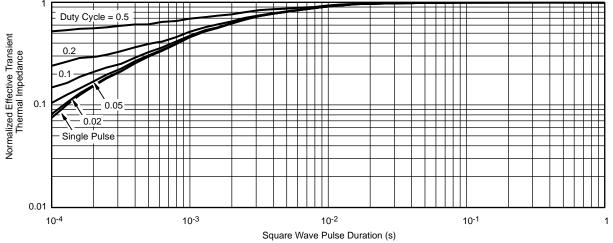






#### Power Derating, Junction-to-Case

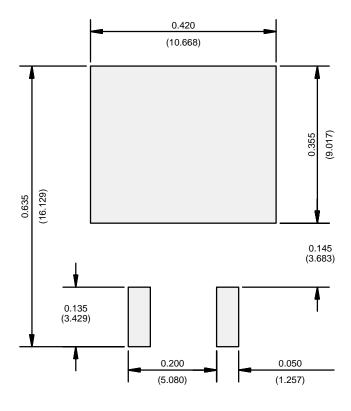
Safe Operating Area, Junction-to-Case



Normalized Thermal Transient Impedance, Junction-to-Case



### RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)



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